



U.S. Army Research, Development and Engineering Command



TECHNOLOGY DRIVEN. WARFIGHTER FOCUSED.

BLACK SILICON FOR NEXT-GENERATION INFRARED SENSORS

Dr. Jeffrey Warrender

August 2012

Report Documentation Page				Form Approved OMB No. 0704-0188	
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1. REPORT DATE AUG 2012		2. REPORT TYPE		3. DATES COVERED 00-00-2012 to 00-00-2012	
4. TITLE AND SUBTITLE Black Silicon for Next-Generation Infrared Sensors				5a. CONTRACT NUMBER	
				5b. GRANT NUMBER	
				5c. PROGRAM ELEMENT NUMBER	
6. AUTHOR(S)				5d. PROJECT NUMBER	
				5e. TASK NUMBER	
				5f. WORK UNIT NUMBER	
7. PERFORMING ORGANIZATION NAME(S) AND ADDRESS(ES) U.S. Army Research, Development and Engineering Command,Picatinny Arsenal,NJ,07806-5000				8. PERFORMING ORGANIZATION REPORT NUMBER	
9. SPONSORING/MONITORING AGENCY NAME(S) AND ADDRESS(ES)				10. SPONSOR/MONITOR'S ACRONYM(S)	
				11. SPONSOR/MONITOR'S REPORT NUMBER(S)	
12. DISTRIBUTION/AVAILABILITY STATEMENT Approved for public release; distribution unlimited					
13. SUPPLEMENTARY NOTES Presented at the 2nd Multifunctional Materials for Defense Workshop in conjunction with the 2012 Annual Grantees'/Contractors' Meeting for AFOSR Program on Mechanics of Multifunctional Materials & Microsystems Held 30 July - 3 August 2012 in Arlington, VA. Sponsored by AFRL, AFOSR, ARO, NRL, ONR, and ARL.					
14. ABSTRACT					
15. SUBJECT TERMS					
16. SECURITY CLASSIFICATION OF:			17. LIMITATION OF ABSTRACT Same as Report (SAR)	18. NUMBER OF PAGES 34	19a. NAME OF RESPONSIBLE PERSON
a. REPORT unclassified	b. ABSTRACT unclassified	c. THIS PAGE unclassified			

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Precision-guided munitions



Situational Awareness



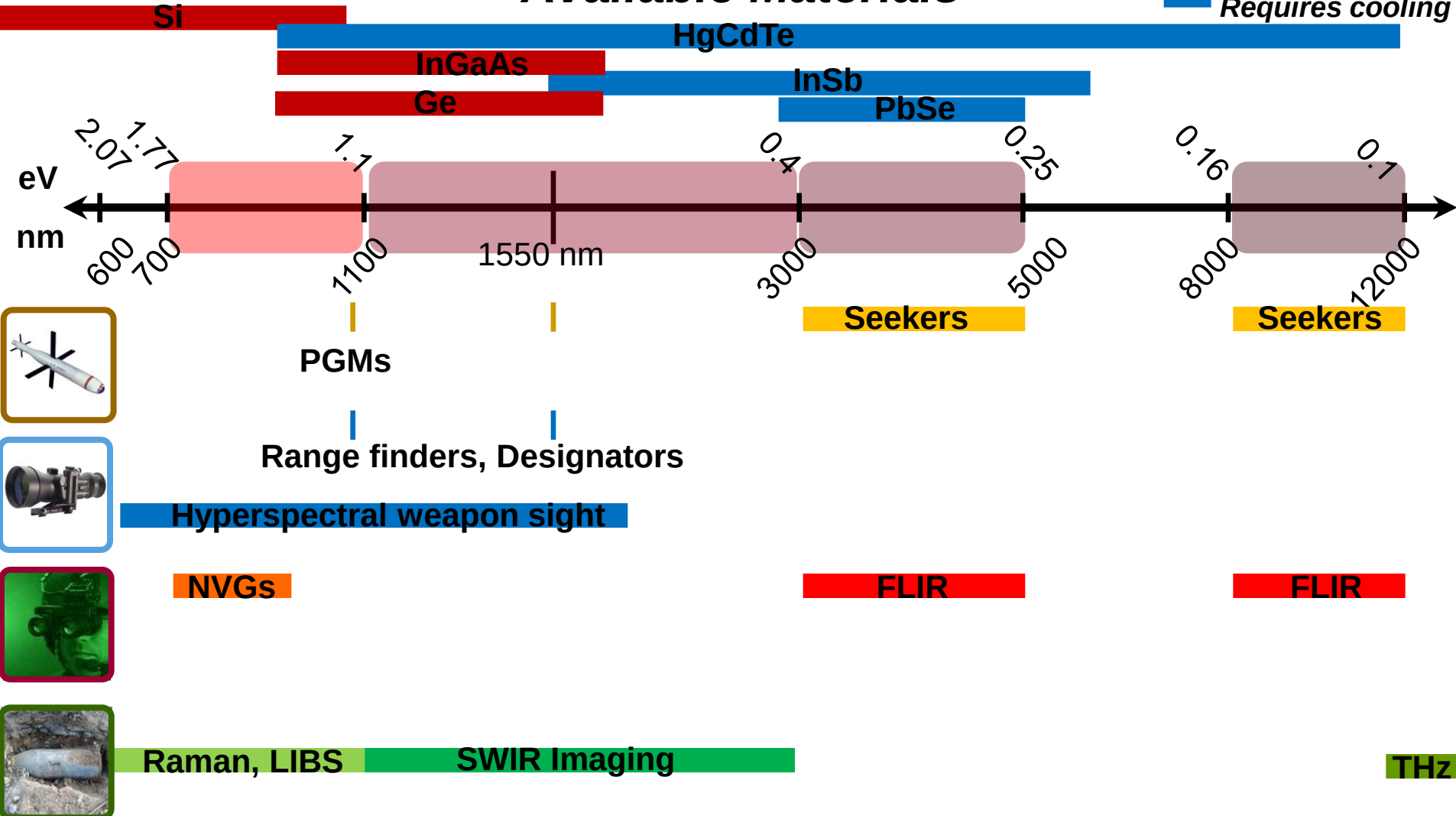
Photovoltaics



Standoff Explosive Detection

Available Materials

— RT operation
— Requires cooling



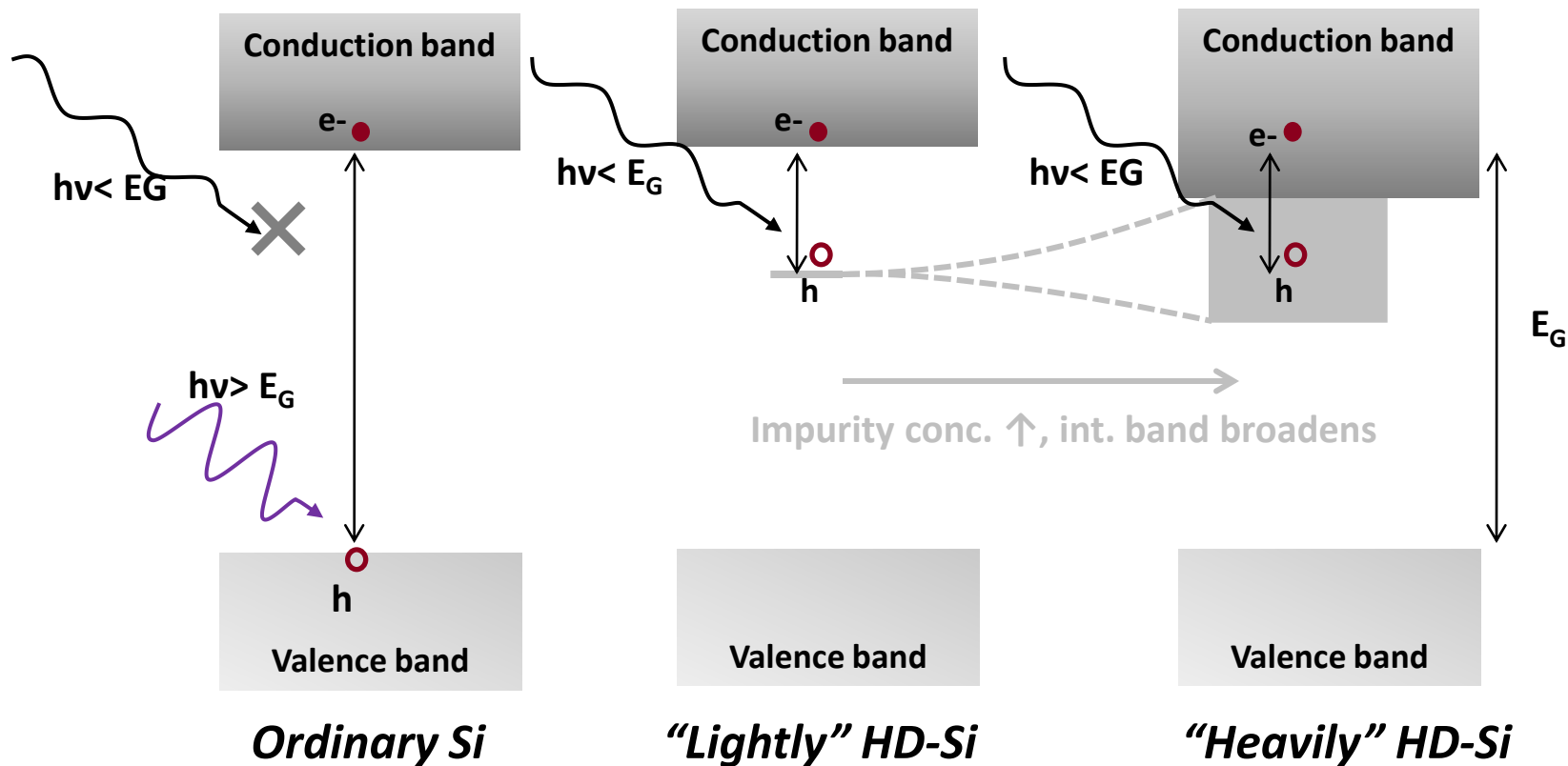
Silicon-based IR optoelectronics

Silicon is...

- +** {
 - Ubiquitous**
 - Inexpensive**
 - Well-characterized**
 - Easy to integrate with readout circuitry**
- {
 - Non-absorbing for wavelengths > 1100 nm**

Can we dope Si to see IR response?

Hyperdoping: Create mid gap states



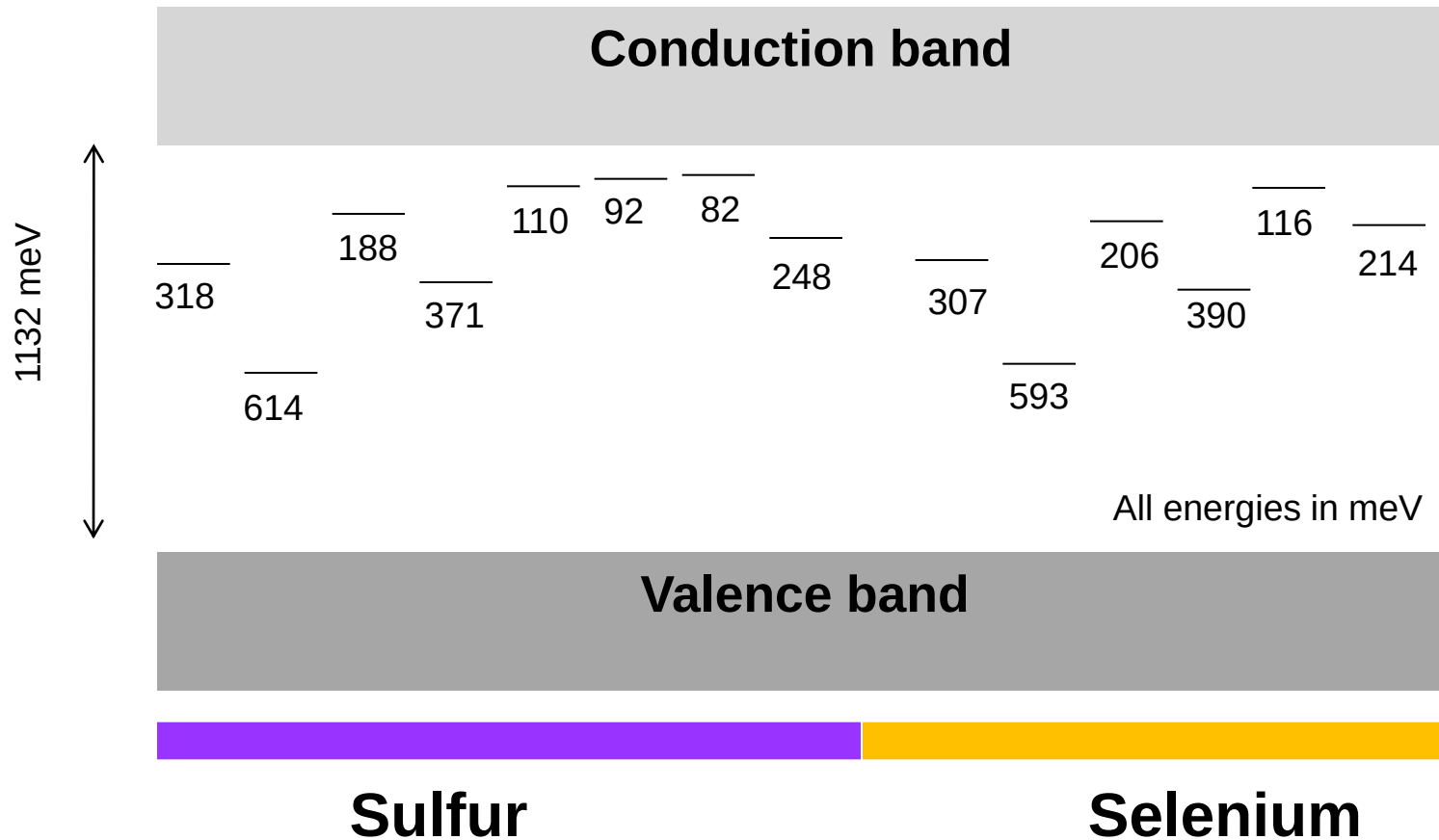
Chalcogen dopants in silicon

The Periodic Table of the Elements

1 H Hydrogen 1.00794																	2 He Helium 4.003														
3 Li Lithium 6.941	4 Be Beryllium 9.012182											5 B Boron 10.811	6 C Carbon 12.0107	7 N Nitrogen 14.00674	8 O Oxygen 15.9994	9 F Fluorine 18.9984032	10 Ne Neon 20.1797														
11 Na Sodium 22.989770	12 Mg Magnesium 24.3050											13 Al Aluminum 26.981538	14 Si Silicon 28.0855	15 P Phosphorus 30.97376	16 S Sulfur 32.066	17 Cl Chlorine 35.4527	18 Ar Argon 39.948														
19 K Potassium 39.0983	20 Ca Calcium 40.078	21 Sc Scandium 44.955910	22 Ti Titanium 47.867	23 V Vanadium 50.9415	24 Cr Chromium 51.9961	25 Mn Manganese 54.938049	26 Fe Iron 55.845	27 Co Cobalt 58.933200	28 Ni Nickel 58.6934	29 Cu Copper 63.546	30 Zn Zinc 65.39	31 Ga Gallium 69.723	32 Ge Germanium 72.61	33 As Arsenic 74.9216	34 Se Selenium 78.96	35 Br Bromine 79.904	36 Kr Krypton 83.80														
37 Rb Rubidium 85.4678	38 Sr Strontium 87.62	39 Y Yttrium 88.90585	40 Zr Zirconium 91.224	41 Nb Niobium 92.90638	42 Mo Molybdenum 95.94	43 Tc Technetium (98)	44 Ru Ruthenium 101.07	45 Rh Rhodium 102.90550	46 Pd Palladium 106.42	47 Ag Silver 107.8682	48 Cd Cadmium 112.411	49 In Indium 114.818	50 Sn Tin 118.710	51 Sb Antimony 121.760	52 Te Tellurium 127.60	53 I Iodine 126.90447	54 Xe Xenon 131.29														
55 Cs Cesium 132.90545	56 Ba Barium 137.327	57 La Lanthanum 138.9055	72 Hf Hafnium 178.49	73 Ta Tantalum 180.9479	74 W Tungsten 183.84	75 Re Rhenium 186.207	76 Os Osmium 190.23	77 Ir Iridium 192.217	78 Pt Platinum 195.078	79 Au Gold 196.96655	80 Hg Mercury 200.59	81 Tl Thallium 204.3833	82 Pb Lead 207.2	83 Bi Bismuth 208.98038	84 Po Polonium (209)	85 At Astatine (210)	86 Rn Radon (222)														
87 Fr Francium (223)	88 Ra Radium (226)	89 Ac Actinium (227)	104 Rf Rutherfordium (261)	105 Db Dubnium (262)	106 Sg Seaborgium (263)	107 Bh Bohrium (262)	108 Hs Hassium (265)	109 Mt Meitnerium (266)	110 (269)	111 (272)	112 (277)	113 	114 																		
																		58 Ce Cerium 140.116	59 Pr Praseodymium 140.90765	60 Nd Neodymium 144.24	61 Pm Promethium (145)	62 Sm Samarium 150.36	63 Eu Europium 151.964	64 Gd Gadolinium 157.25	65 Tb Terbium 158.92534	66 Dy Dysprosium 162.50	67 Ho Holmium 164.93032	68 Er Erbium 167.26	69 Tm Thulium 168.93421	70 Yb Ytterbium 173.04	71 Lu Lutetium 174.967
																		90 Th Thorium 232.0381	91 Pa Protactinium 231.03588	92 U Uranium 238.0289	93 Np Neptunium (237)	94 Pu Plutonium (244)	95 Am Americium (243)	96 Cm Curium (247)	97 Bk Berkelium (247)	98 Cf Californium (251)	99 Es Einsteinium (252)	100 Fm Fermium (257)	101 Md Mendelevium (258)	102 No Nobelium (259)	103 Lr Lawrencium (262)

Chalcogen dopants in silicon

Binding energies of chalcogen centers in Si



Janzen et al., *Phys Rev B* (1984)

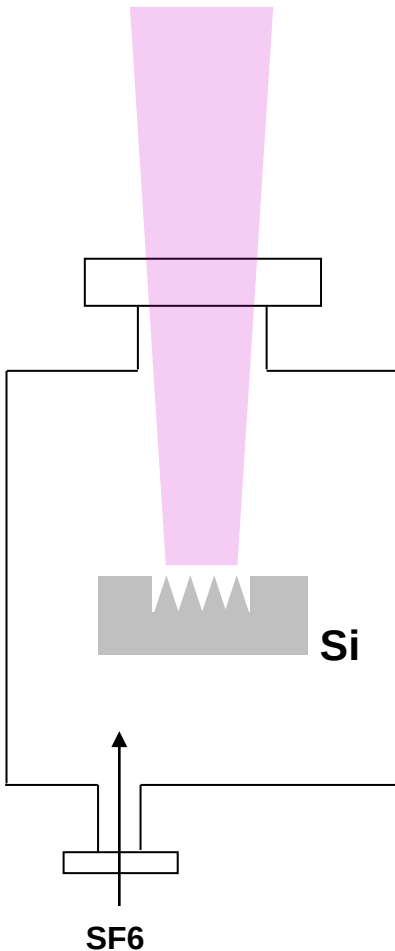
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Spiked Black Silicon

Harvard (Mazur)/ Sionyx

Pulsed laser



Crouch et al, *Appl Phys Lett* (2004)

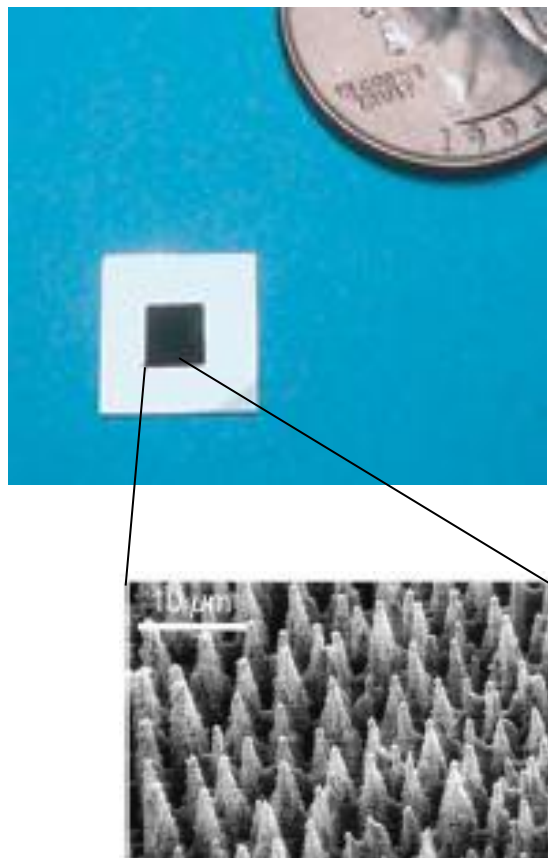
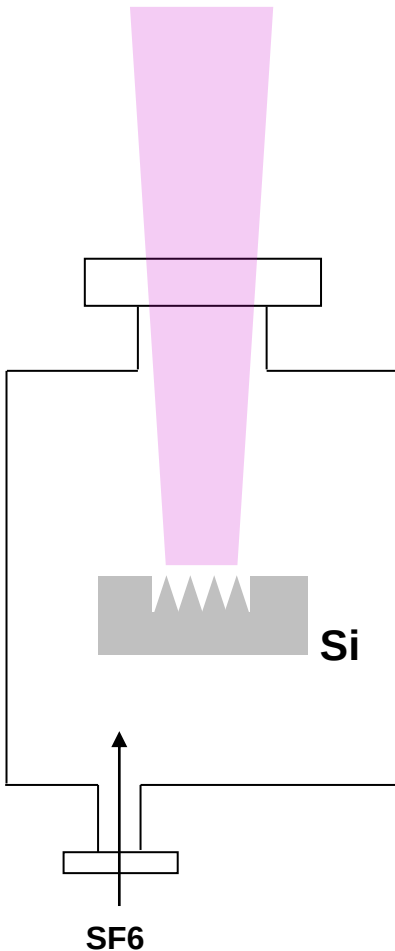
TECHNOLOGY DRIVEN. WARFIGHTER FOCUSED.

Spiked Black Silicon

Harvard (Mazur)/ Sionyx



Pulsed laser



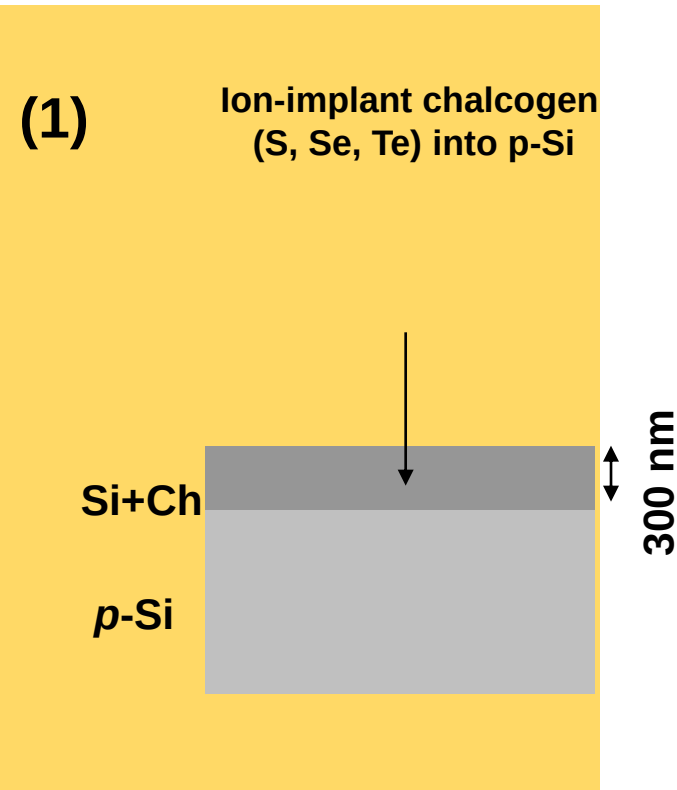
Crouch et al, Appl Phys Lett (2004)

TECHNOLOGY DRIVEN. WARFIGHTER FOCUSED.



Flat Black Silicon

Harvard (Aziz)/ ARDEC



Kim et al, *Appl Phys Lett* (2006)
Tabbal et al, *JVST B* (2007)

Bob et al, submitted to *J Appl Phys*

TECHNOLOGY DRIVEN. WARFIGHTER FOCUSED.

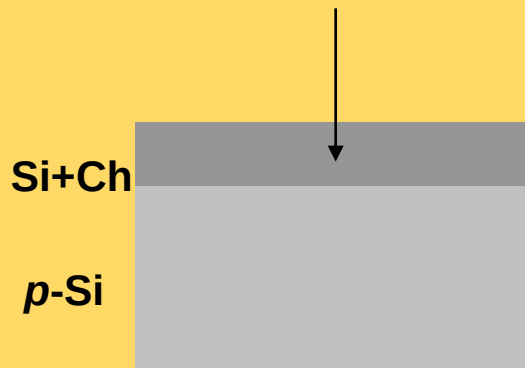


Flat Black Silicon

Harvard (Aziz)/ ARDEC

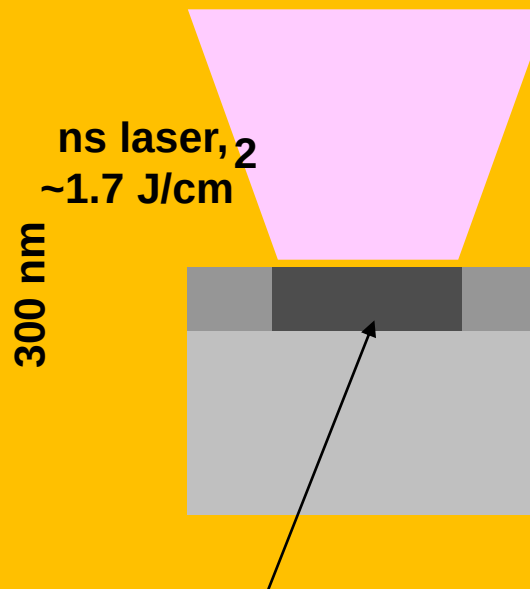
(1)

Ion-implant chalcogen
(S, Se, Te) into p-Si



(2)

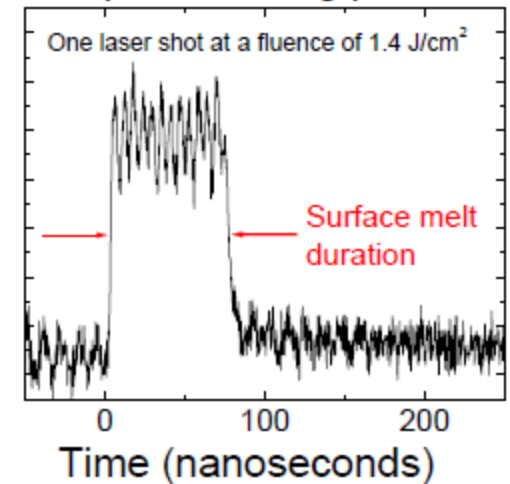
Pulsed-laser melting (PLM)
“heals” implant damage



Crystalline Si,
supersaturated in Ch, *n*-
type

Reflectivity Signal

Temporal melting profile of Si



Kim et al, *Appl Phys Lett* (2006)
Tabbal et al, *JVST B* (2007)

Bob et al, *JAP* (2010)

Benet Labs' Black Silicon setup

Nd:YAG laser
1064/532/355/266 nm
4 ns pulse duration



$\lambda/2$ plate

Ar ion laser (CW)
488 nm
1.2 W



Lenses

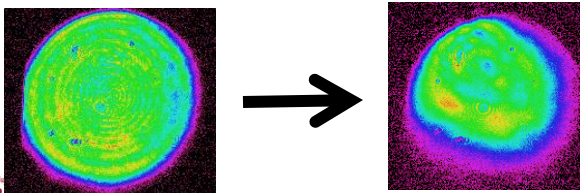
Motorized stage

Fast photodiode

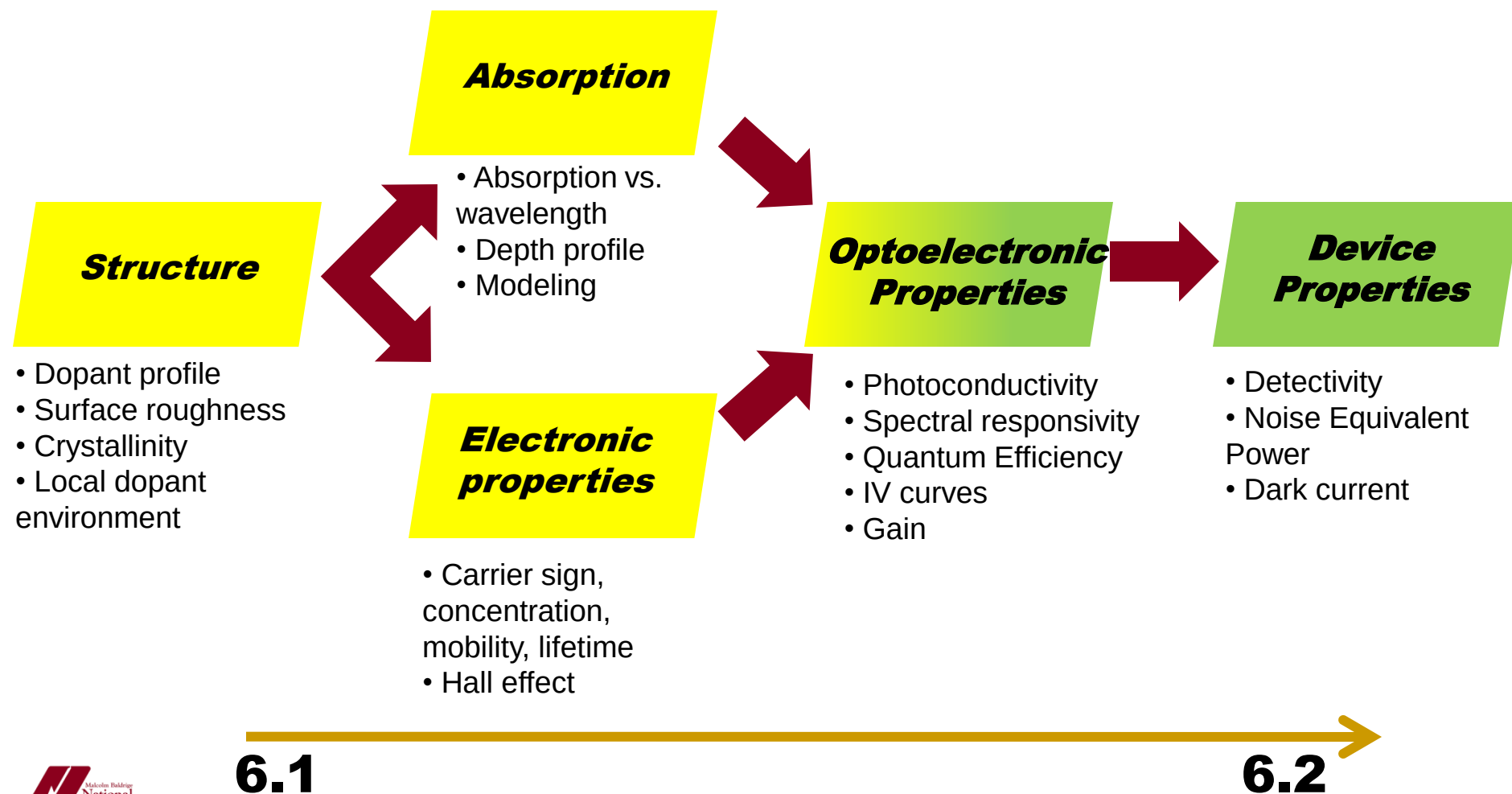
Vacuum chamber

Oscilloscope

Relay-image w/pinhole

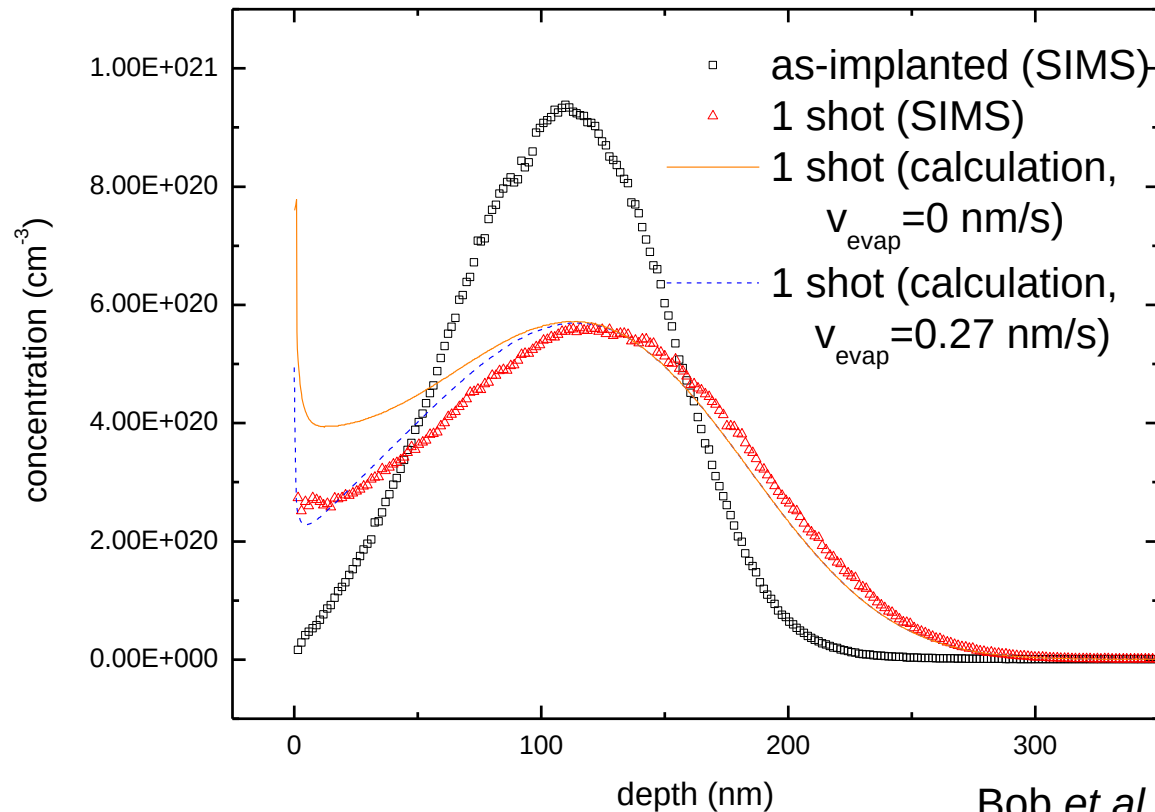


Characterization Logical Flow



Structure

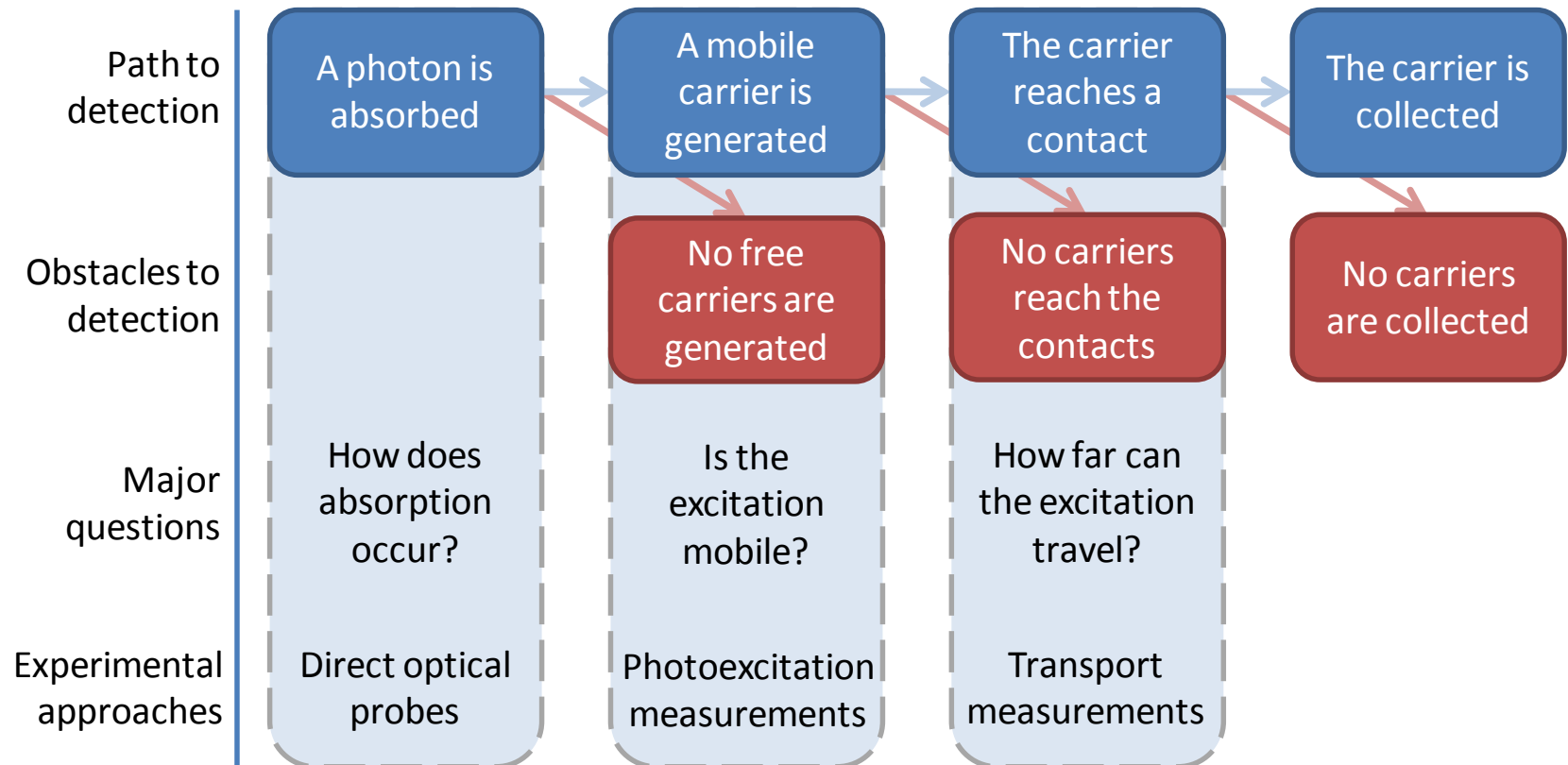
Dopant depth profile evolution



Bob et al, JAP (2010)

BUT, as laser shots $\uparrow$, $v_{\text{evap}} \downarrow$

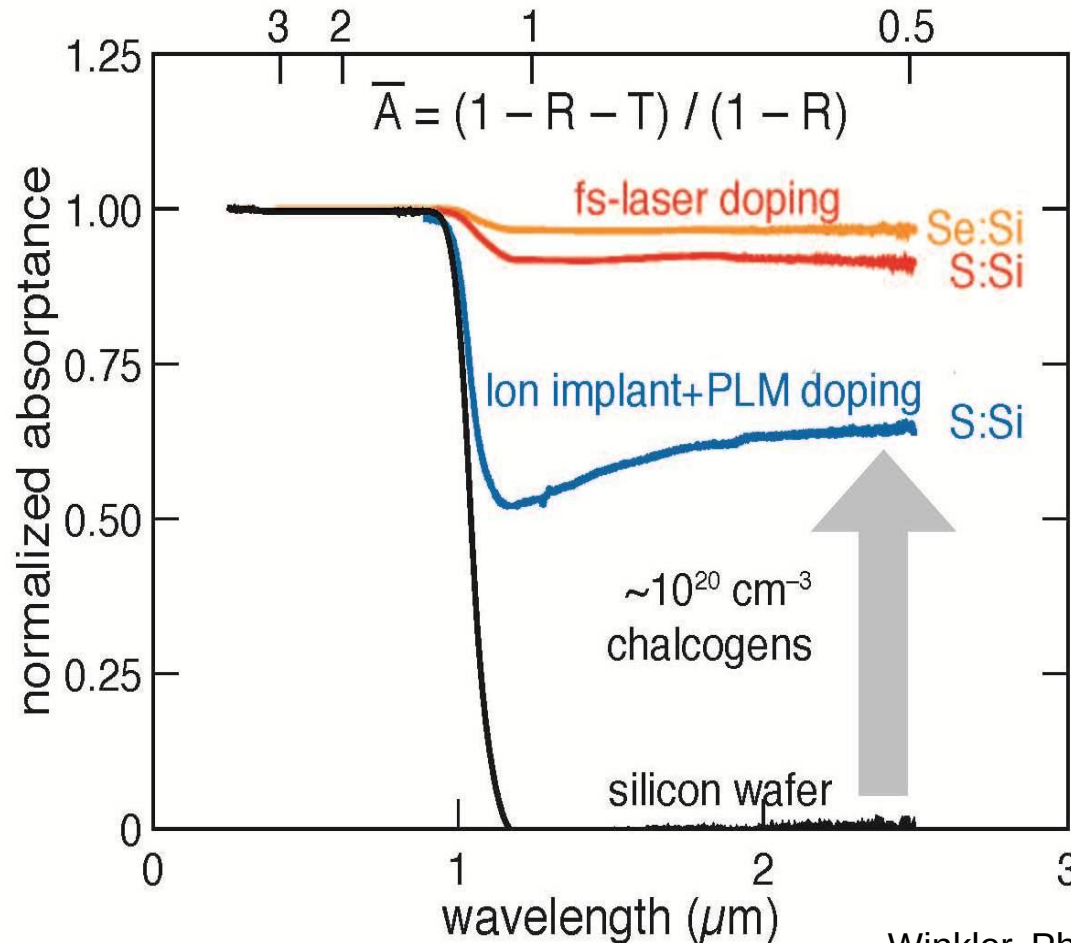
Our approach to studying hyperdoped silicon



Absorption

photon energy (eV)

Absorption

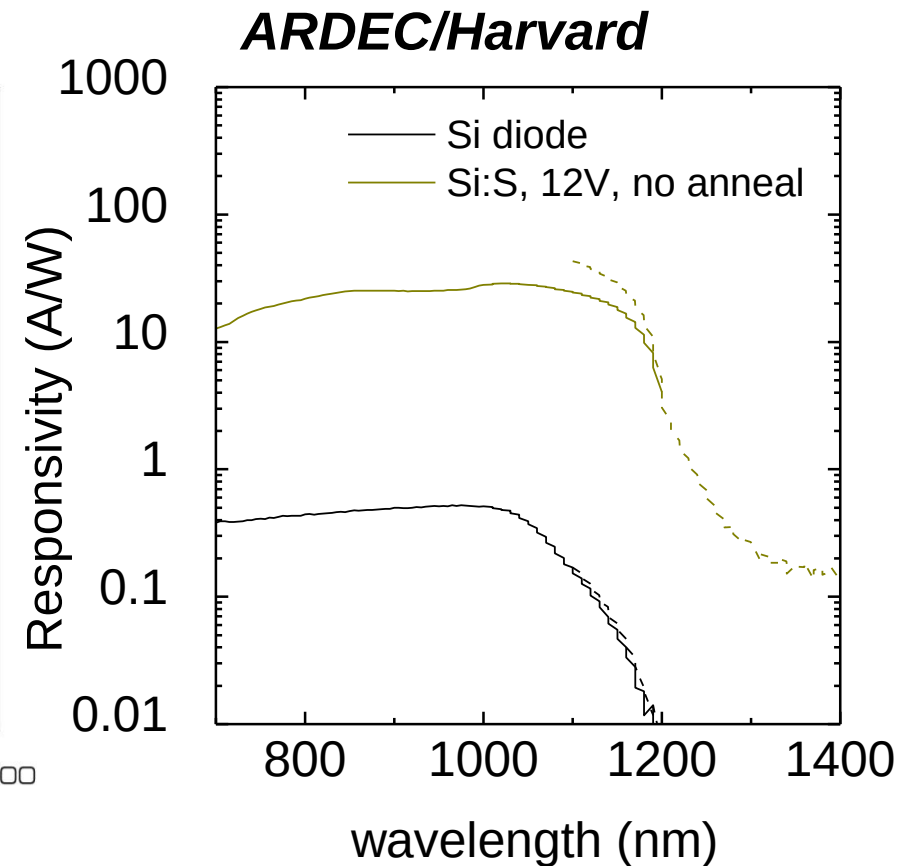
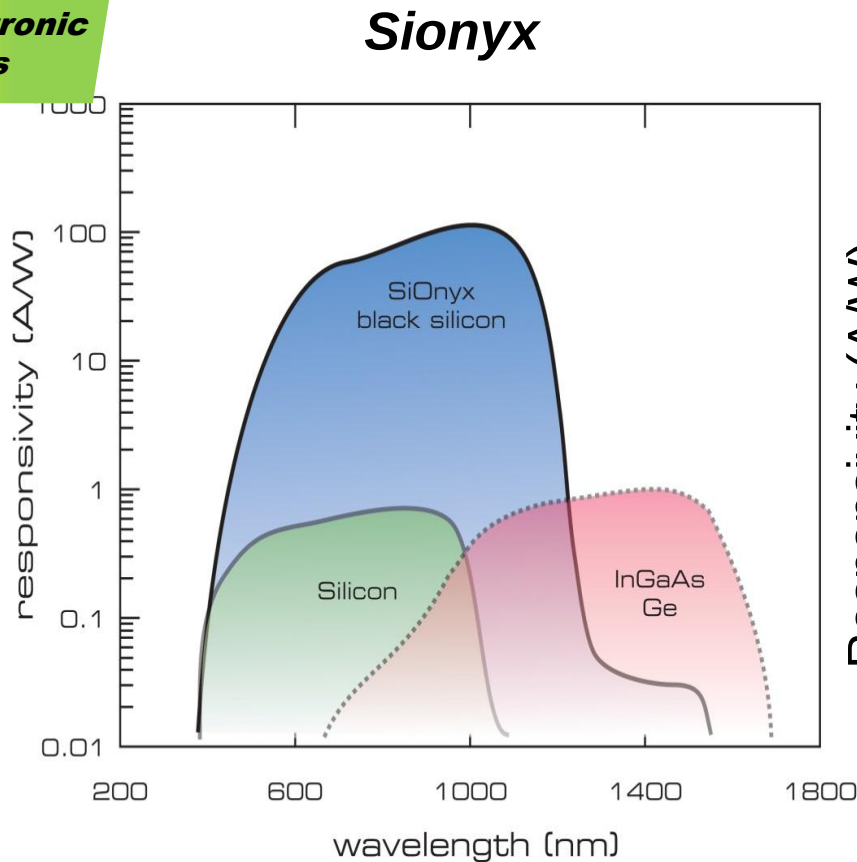


Winkler, Ph.D. thesis, Harvard (2010)

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Responsivity comparison

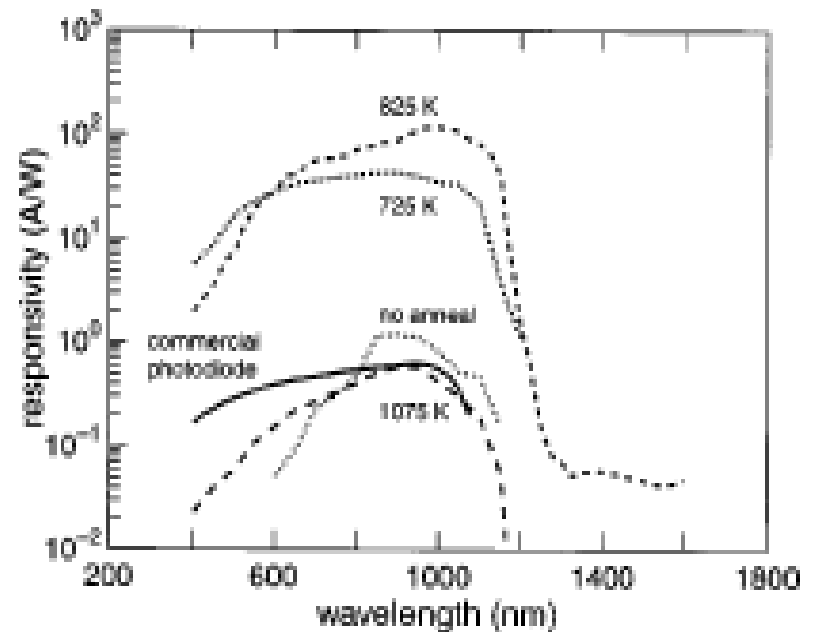
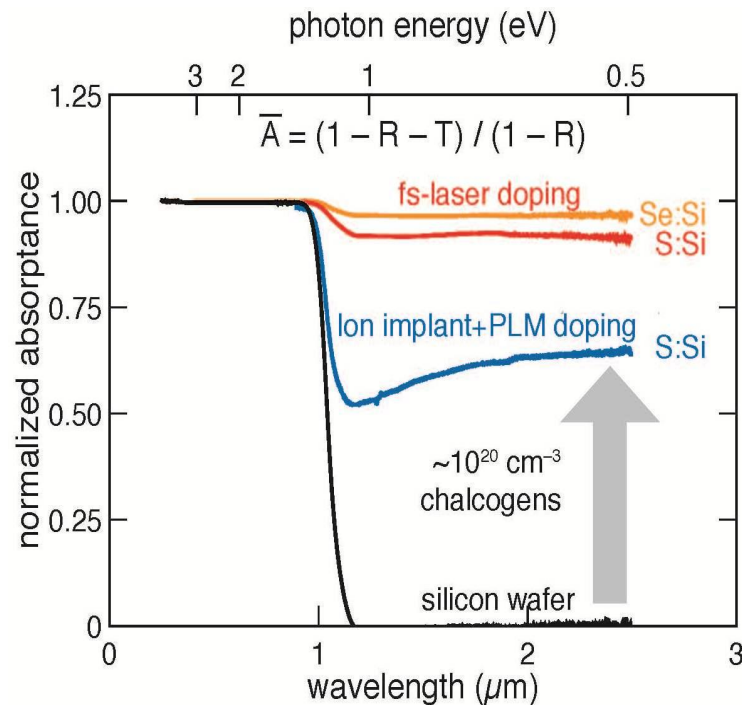
**Optoelectronic
Properties**



Said et al, *APL* (2011)

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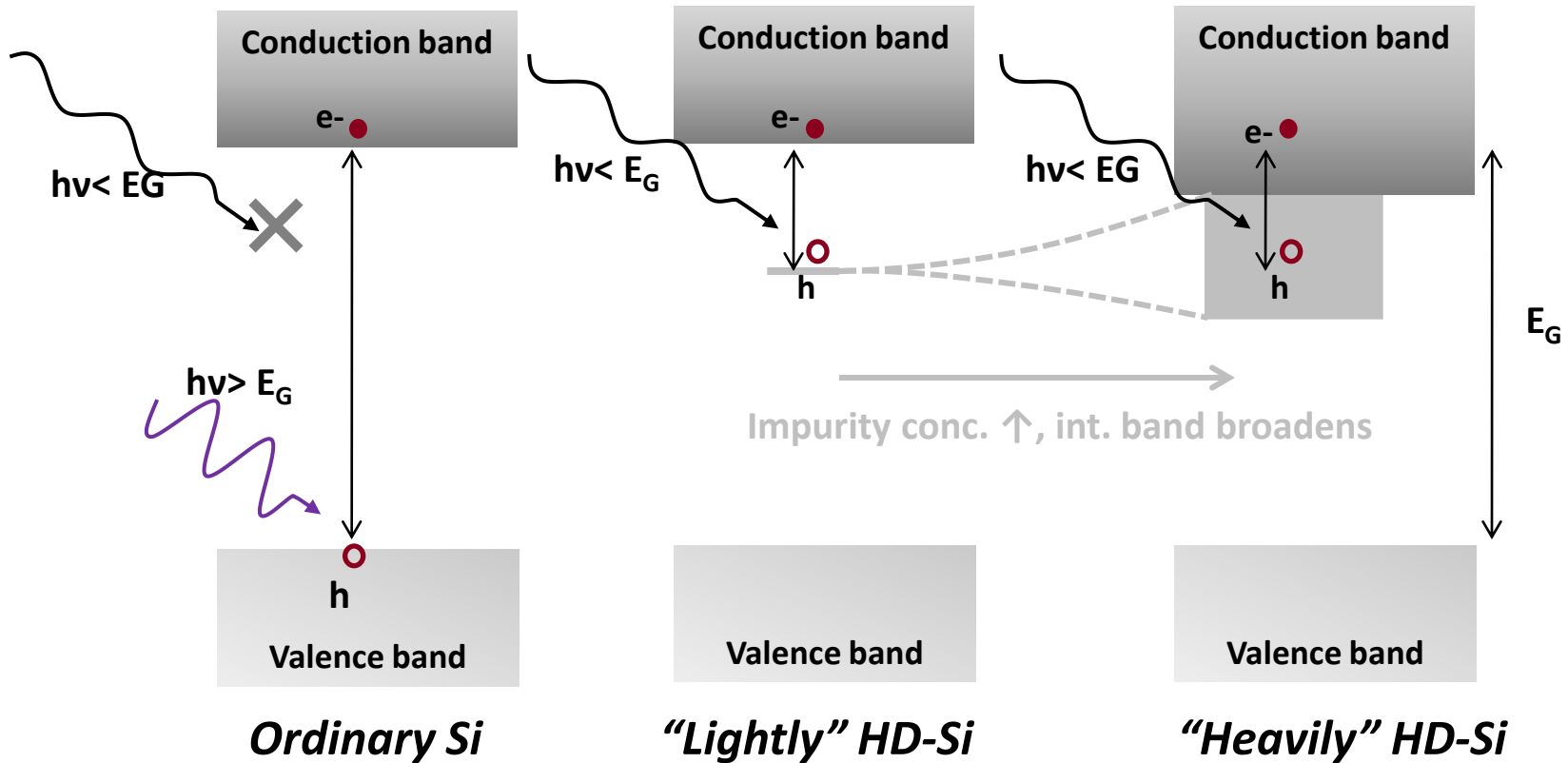
An apparent conundrum



Strong, broadband absorption...

...but no device response

Possible reconciliation



Other Strategies to Try

Less dopant

Change dopant

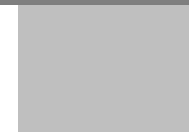
Add dopant

Conduction band

Conduction band

Conduction band

Conduction band



Valence band

Valence band

Valence band

Valence band

Move states out of
conduction band

Move states
deeper into band
gap

Compensate
impurity band
gap

The Larger Black Silicon Universe

Stakeholders

Extended
IR needed?
Existing
BSi ok?

System

	CERDEC-NVESD	Digital Nightvision	X	
	USMC	CLRF	X	X
	ONR	DETECT, CLRF	X	X
	White Sands Missile Range	Airborne Laser	X	
	ARDEC	Precision-guided	X	X

Research Groups

	Harvard Aziz
	ARDEC-Benet Warrender
	RPI Persans
	MIT Buonassisi
	Harvard Mazur
	MIT Gradecak
	MIT Grossman
	Illinois Ertekin
	Sionyx Pralle, Carey

Extended IR response,
optoelectronic
charazterization

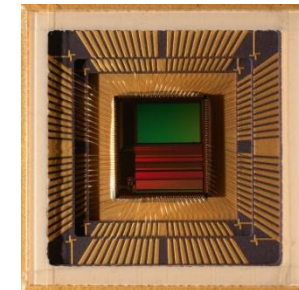
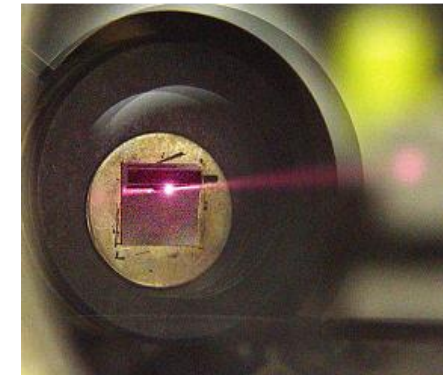
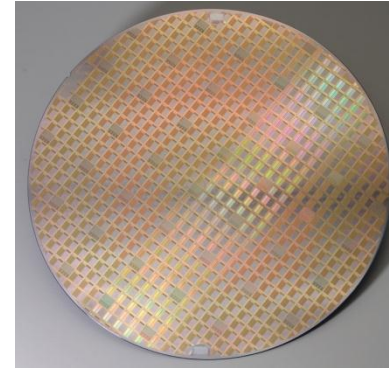
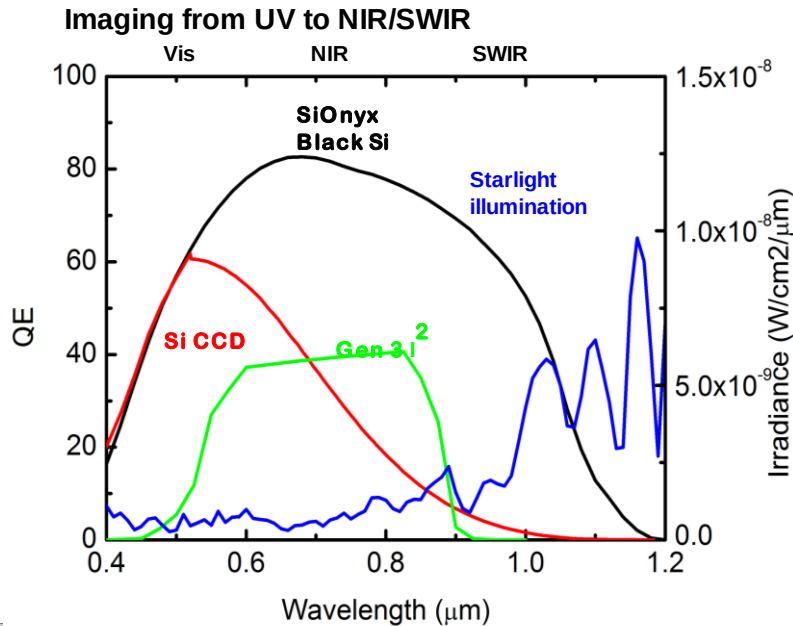
Characterization of fs-
structured Black Silicon

First principles modeling

Commercialization

TECHNOLOGY DRIVEN. WARFIGHTER FOCUSED.

SiOnyx IR CMOS: Black Silicon enhanced imaging



- Low cost 8" CMOS manufacturing
- Low Noise (Read noise ~2 e/pix)
(Dark Current <8e/pix/frame)
- Low Power (300 mW @ 800x600)
- Compact Size
- TRL 6 imaging device
- TRL 6 wafer process



mupralle@sionyx.com, 978-922-0684x127

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Outreach

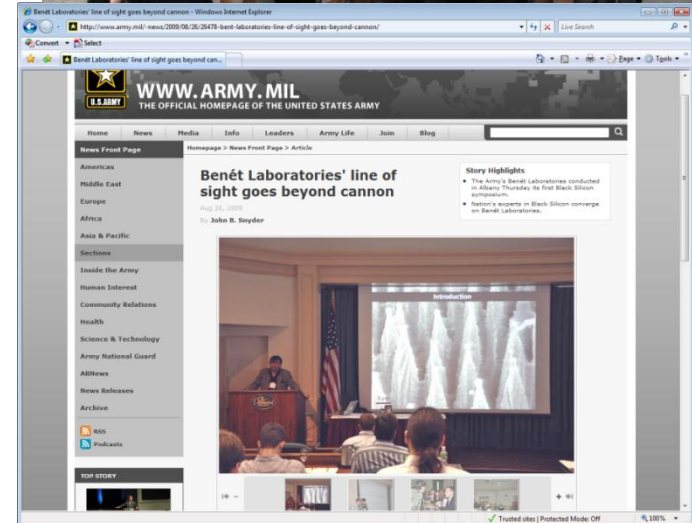
Black Silicon Quarterly

- News and recent black silicon goings-on
- Send an email to jeffrey.m.warrender.civ@mail.mil to be added to distribution



Black Silicon Symposium

- Held in Albany, NY
- **August 9-10**



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Summary and Outlook

- **Laser hyperdoped “black” silicon can be made by two different approaches**
 - Similar properties
 - “Flat” black silicon easier to study
- **Strong sub band gap absorption**
- **High EQE out to 1200 nm**
- **ARDEC seeks to extend strong device response to 1700 nm**
- **Fundamental and practical questions abound**

jeffrey.m.warrender.civ@mail.mil

BACKUP SLIDES

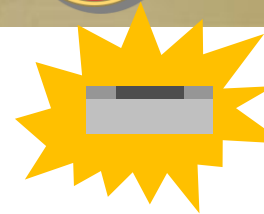
Research interests at Benet

- Extending black silicon's IR response
- Characterizing the properties of ns-spiked black Si
- Exploring broader slice of parameter space
 - Non-chalcogen dopants, thick layers, 5 ns pulses, non-UV wavelengths
- Increasing process cleanliness
- Black Si photovoltaics

Assets



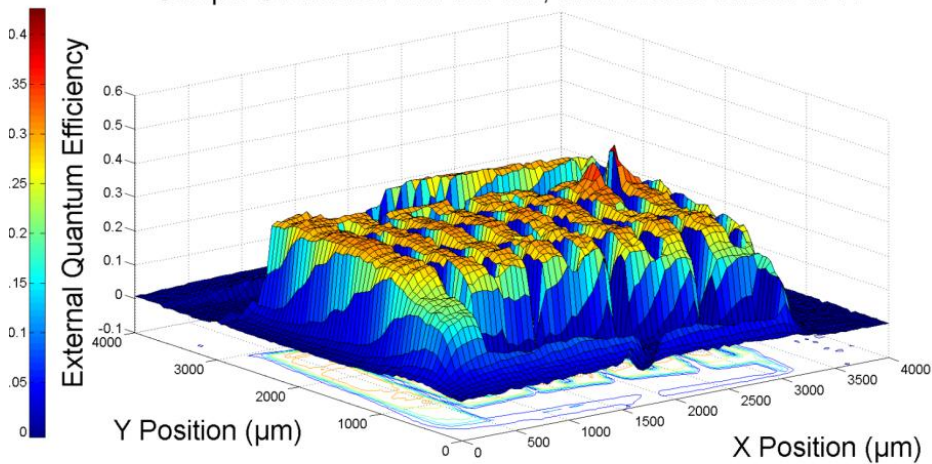
Laser/tool	Purpose	Capabilities
Ekspla NL313	Laser melting	532 nm/ 355 nm 800/500 mJ output 5 ns pulse duration
Coherent I-306	Surface reflectivity	514/488/458 nm 2.4/1.8/0.42 W output CW
Resonetics Excimer system	Laser melting	248 nm 400 mJ output 20 ns pulse duration
Vacuum chamber with motorized stage	Wafer-scale clean processing	150 mm Si wafer processing
Dual-beam FE-SEM/FIB	TEM sample prep, High-res imaging	System spec pending



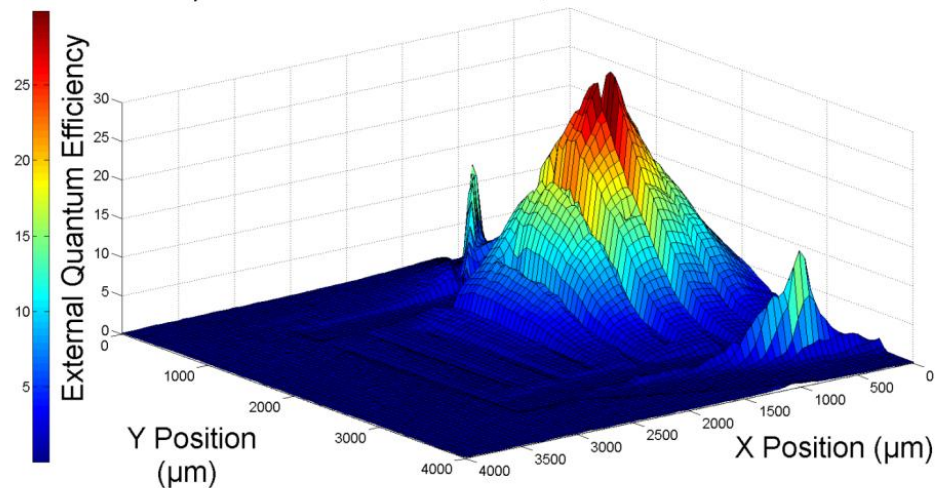
Gain is spatially inhomogeneous

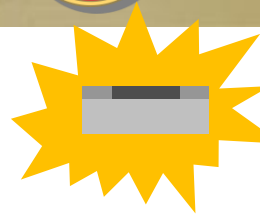
**Optoelectronic
Properties**

Sample U rastered with 650 nm, and reverse biased at 1V



Sample U rastered with 980 nm, and reverse biased at 12V

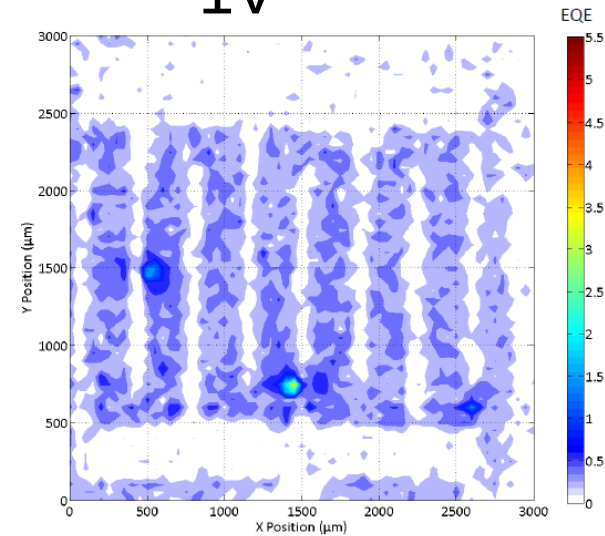




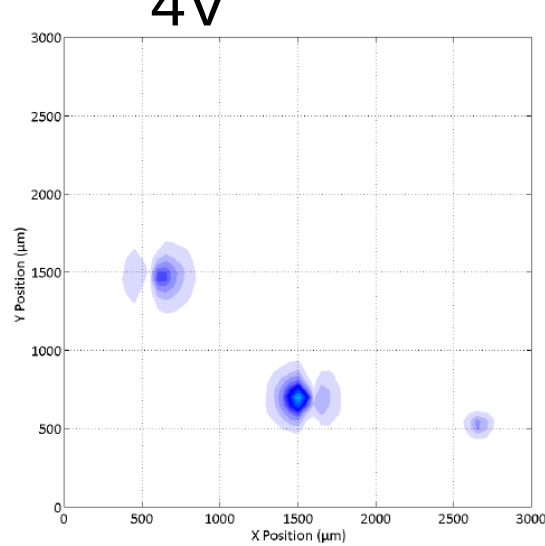
**Optoelectronic
Properties**

Gain is spatially inhomogeneous

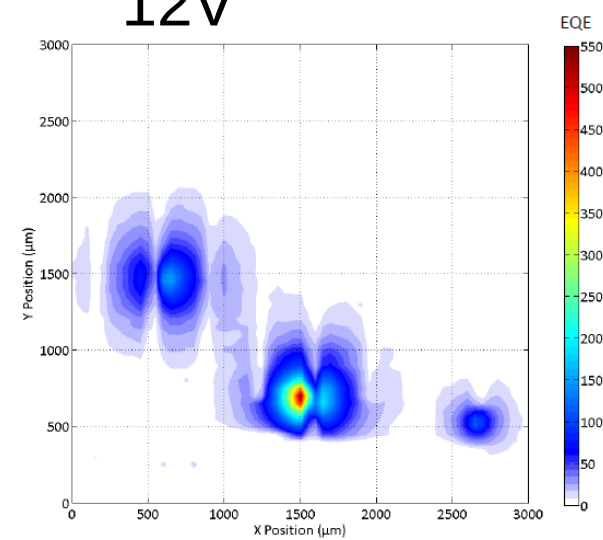
1V



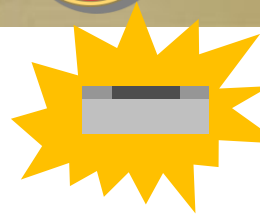
4V



12V



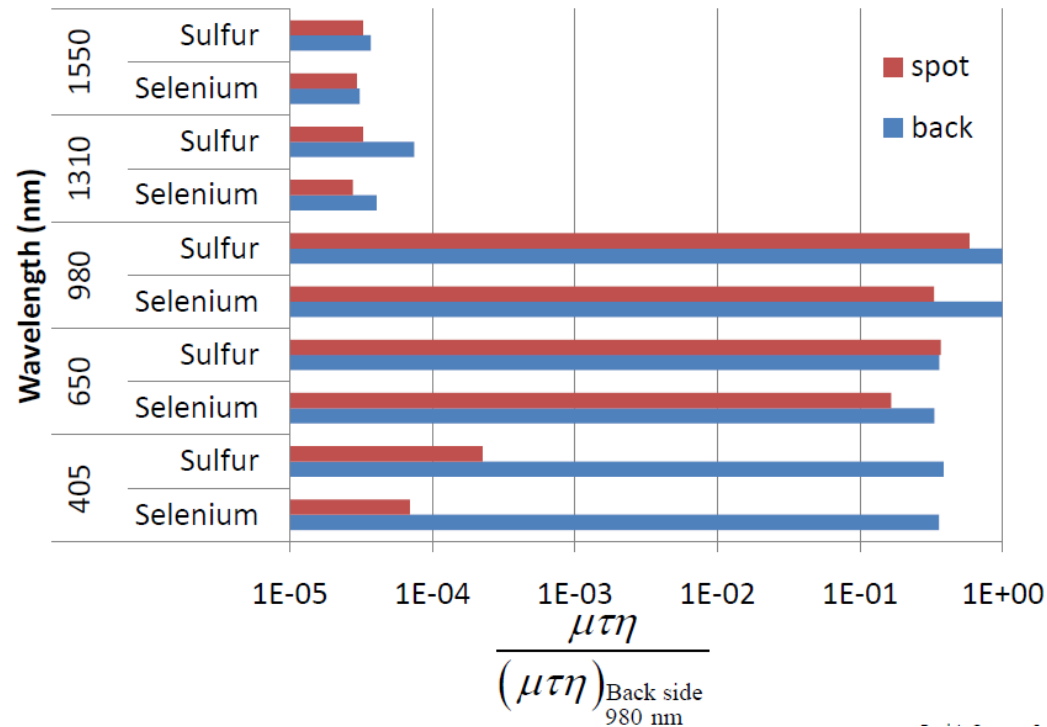
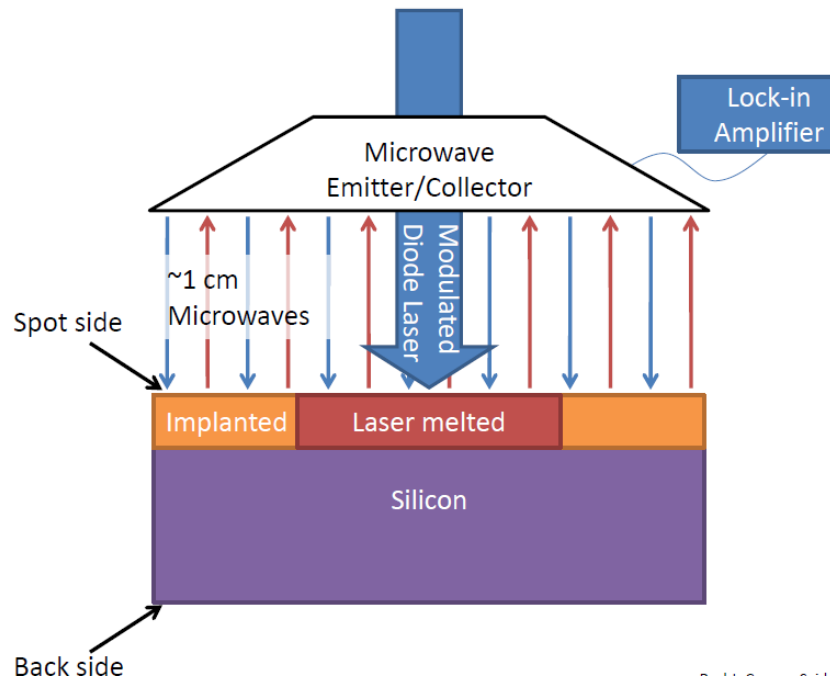
1e15/cm² S in Si, 4 laser shots, Ti/Ni/Ag contacts, 980 nm probe laser, reverse bias



...but the story gets even weirder

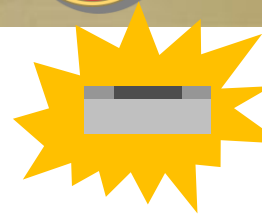
Optoelectronic Properties

Microwave reflectivity



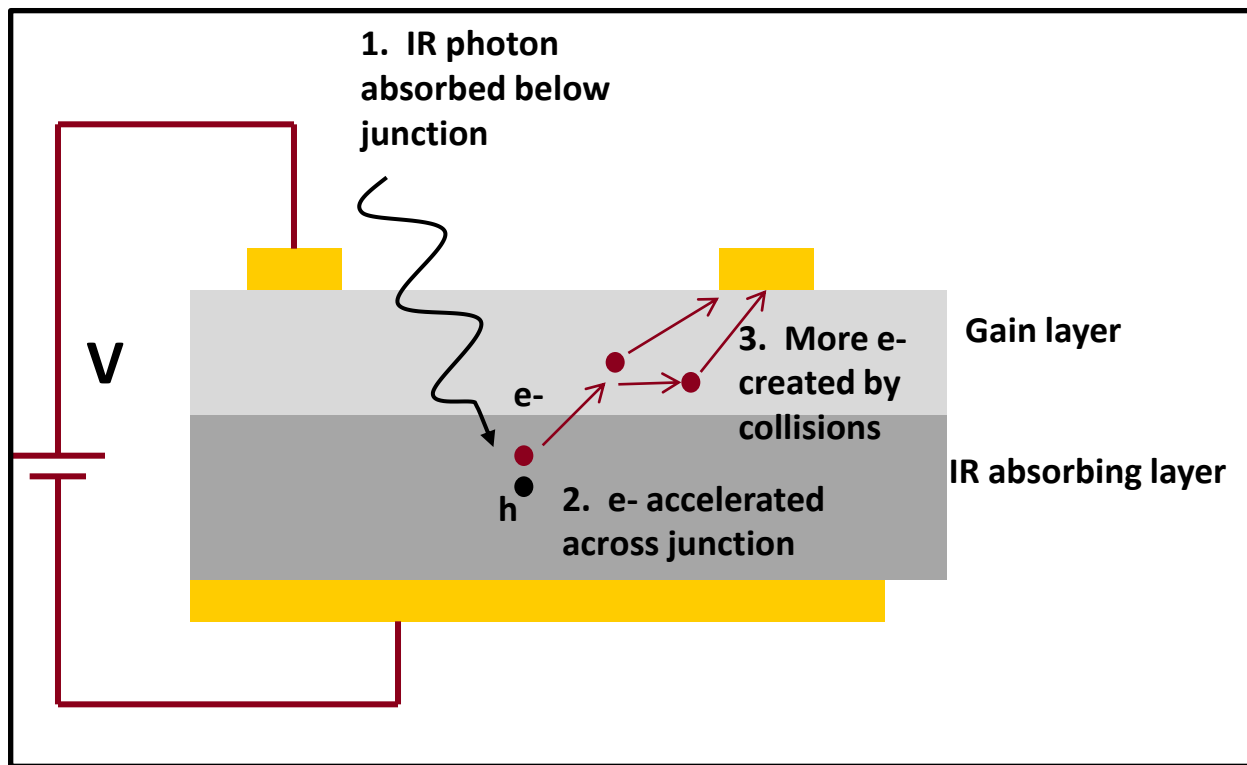
No detectable photoconductivity in the Si:S layer!

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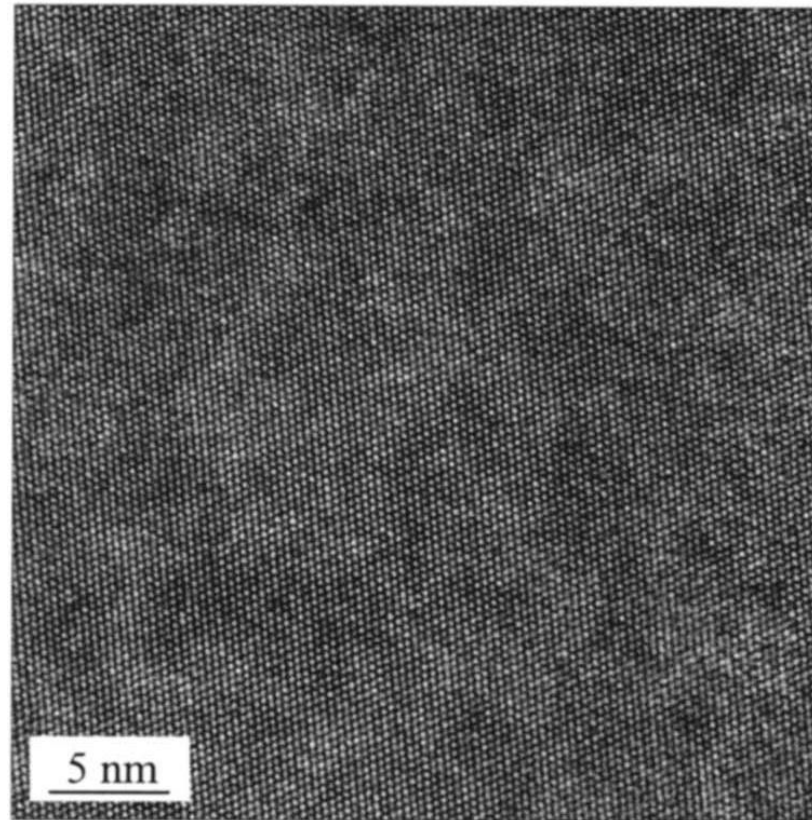


**Optoelectronic
Properties**

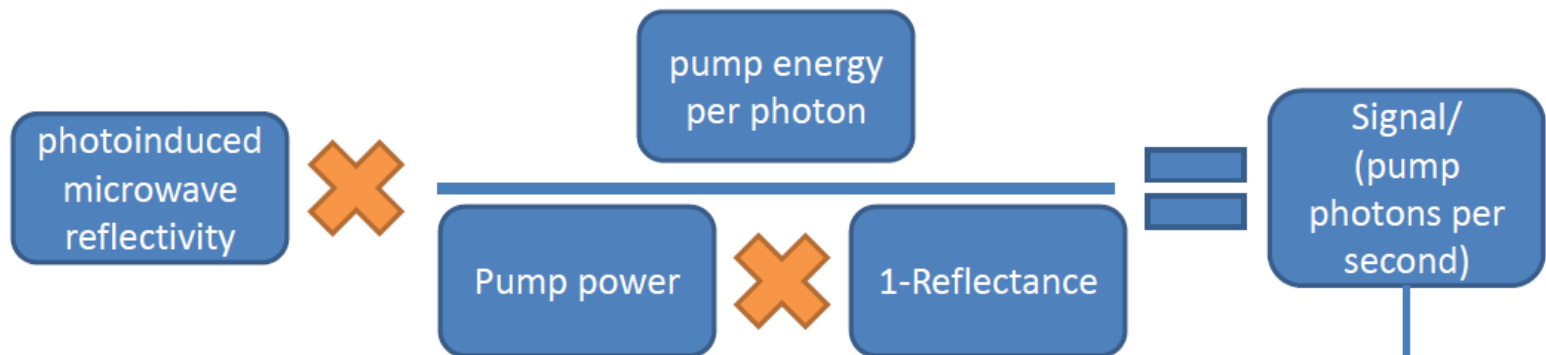
Gain without photoconductivity?



XTEM lattice image of PLM'd material



Data were converted to signal per (pump photons per second)



$$\frac{C\Delta\sigma}{\text{photons / sec}} = \frac{Ce\mu\Delta n}{\text{photons / sec}} = \frac{Ce\mu\tau g}{\text{photons / sec}} = \frac{(Ce\mu\tau) \times (\text{photons / sec}) \times (\eta)}{\text{photons / sec}} = Ce\mu\tau\eta$$

Constant dependent on apparatus not sample or pump

Taking the ratio of two measurements removes the influence of the experimental apparatus (C cancels out)